



SOT566-3

plastic, heatsink small outline package; 24 leads; low stand-off height, 1.0 mm pitch, 15.9 mm x 11.0 mm x 3.35 mm body

21 August 2018

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	HSOP24
Package type industry code	HSOP24
Package style descriptive code	HSOP (heatsink small outline package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	23-07-2003
Manufacturer package code	SOT566

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	15.8	15.9	16	mm
package width	10.9	11	11.1	mm
seated height	-	3.5	-	mm
package height	3.2	3.35	3.5	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	24	-	



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2 Package outline

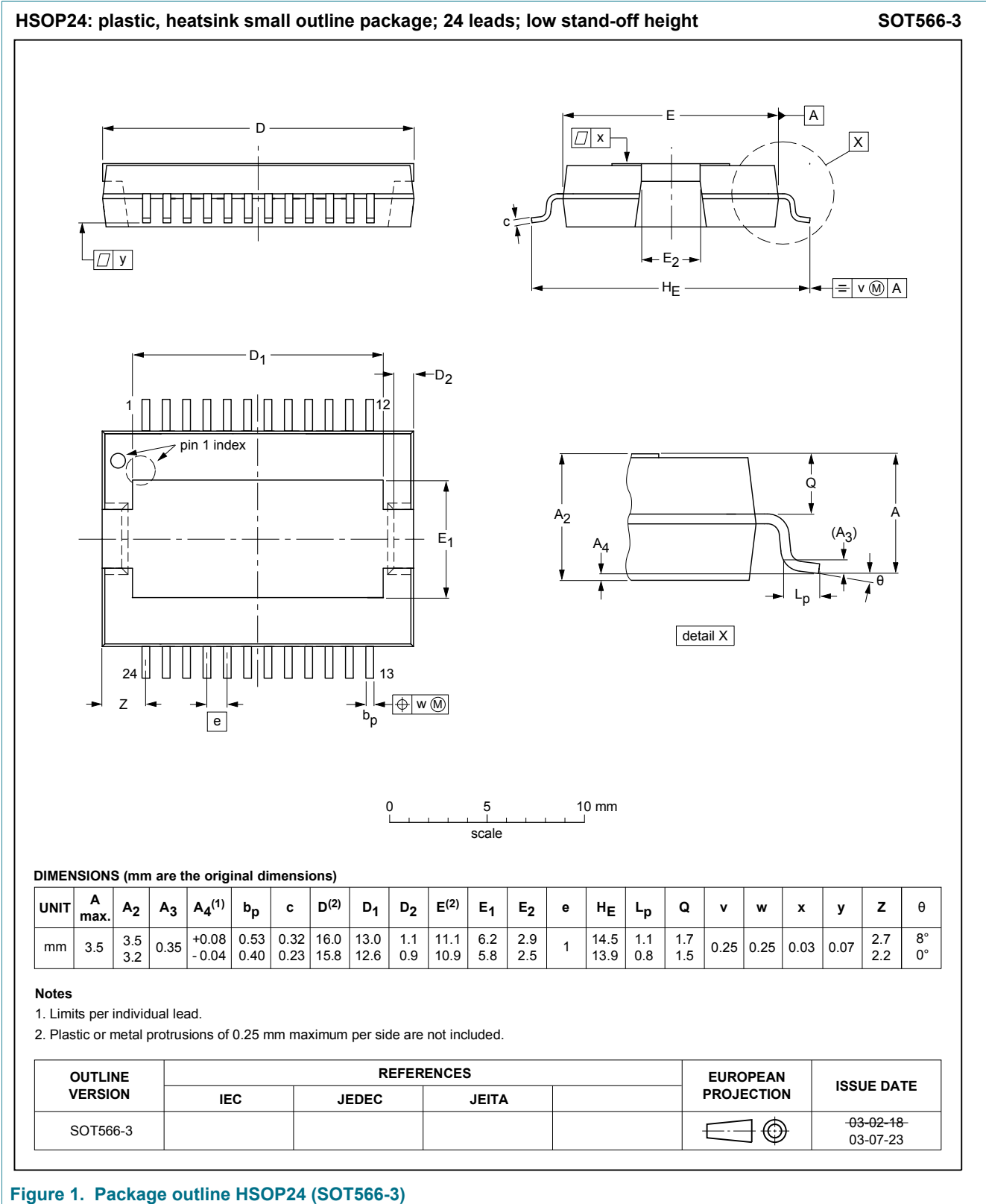


Figure 1. Package outline HSOP24 (SOT566-3)

3 Legal information

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